ABSTRACT OF THE DISCLOSURE

A method of manufacturing a device, including: an adhesive film attaching step of attaching an adhesive film to a back-side surface of a wafer in which devices are formed respectively in a plurality of regions demarcated by planned dividing lines formed in a grid pattern in a face-side surface of the wafer; a wafer supporting step of adhering the adhesive film side of the wafer with the adhesive film attached thereto to a surface of a dicing tape attached to an annular frame; a wafer cutting step of holding the dicing tape side of the wafer adhered to the surface of the dicing tape onto a chuck table of a cutting apparatus, and cutting the wafer along the planned dividing lines by use of a cutting blade having an annular knife edge which is V-shaped in sectional shape of a peripheral part thereof; and an adhesive film breaking step of breaking said adhesive film along cutting grooves formed in the wafer, by expanding the dicing tape so as to exert tension on the adhesive film, after the wafer cutting step is performed.

Figure 7